

IN THE CLAIMS:

1. (Currently Amended): A cooling structure for an electronic element, wherein the structure comprises:

an extended portion formed on an inner baffle conductor and contacting an upper surface of a heat-producing electronic element, wherein the inner baffle conductor and the heat-producing electronic element are mounted on an inner circuit substrate;

a plurality of through holes formed on the inner circuit substrate underneath the heat-producing electronic element;

a baffle conductor case surrounding the inner baffle conductor, the extended portion, the heat-producing electronic element, and the inner circuit substrate, the baffle conductor case having an upper side and a lower side;

a radiating plate mounted on the upper side of the baffle; and conductor;

a plurality of baffle conductor case holes through the lower side of the baffle conductor case;

an external circuit substrate with an upper side and a lower side, wherein the upper side of the external circuit substrate comprises a heat sink contacting the lower side of the conductor case; and

a plurality of external circuit substrate holes through external circuit substrate to correspondingly communicate with said conductor case holes of said conductor case.

2. (Canceled).

3. (Currently Amended): The structure as defined in ~~claim 2~~ claim 1, wherein the heat sink is a flat surface made of metal formed on said external circuit substrate by a open mask soldering process.

4. (Original): The structure as defined in claim 3, wherein the metal is lead.

5. (Original): The structure as defined in claim 1, wherein the electronic element is a power amplifying module of a code division multiple access modem.